

### Initial Product/Process Change Notification

Document #:IPCN26815Z Issue Date:11 Apr 2025

Title of Change:	Wafer plating site transfer from PacTech US to PacTech Malaysia		
Proposed Changed Material First Ship Date:	31 Jul 2025 or earlier if approved by customer		
Current Material Last Order Date:	N/A Orders received after the Current Material Last Order Date expiration are to be considered a orders for new changed material as described in this PCN. Orders for current (unchanged) material after this date will be per mutual agreement and current material inventory availability.		
Current Material Last Delivery Date:	N/A The Current Material Last Delivery Date may be subject to change based on build and depletion of the current (unchanged) material inventory.		
Product Category:	Active components – Discrete components		
Contact information:	Contact your local onsemi Sales Office		
PCN Samples Contact:	Contact your local onsemi Sales Office to place sample order.  Sample requests are to be submitted no later than 45 days after publication of this change notification.  Samples delivery timing will be subject to request date, sample quantity and special custom packing/label requirements.		
Additional Reliability Data:	Contact your local onsemi Sales Office		
Type of Notification:	This is an Initial Product/Process Change Notification (IPCN) sent to customers. An IPCN is advance notification about an upcoming change and contains general information regarding to change details and devices affected. It also contains the preliminary reliability qualification plate The completed qualification and characterization data will be included in the Fire Product/Process Change Notification (FPCN). This IPCN notification will be followed by a Fire Product/Process Change Notification (FPCN) at least 90 days prior to implementation of the change. In case of questions, contact < PCN.Support@onsemi.com>		
Change Category			
Category	Type of Change		
Process - Wafer Production	SEM-PW-13: Move all or parts of production to a different wafer fab site.		

#### **Description and Purpose:**

onsemi would like to notify customers of a change in wafer plating location for the devices listed in this notification. The products in this notification are currently receiving wafer plating at the PacTech site in the United States. Since the process will be terminated at that location mid-2025, all products will be moved to the PacTech site in Malaysia.

There is no product material change, no product marking change. No change in form, fit, function, or performance is expected.

Change	From	То
Wafer plating - Site Change	PacTech, US	PacTech, Malaysia

TEM001791 Rev. I Page 1 of 3



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Reason / Motivation for Change:	Supply disruption
Anticipated impact on fit, form, function reliability, product safety or manufacturability:	The device will be qualified and validated based on the same Product Specification.  No anticipated impacts.

Sites Affected:

 onsemi Sites
 External Foundry/Subcon Sites

 None
 PacTech, Malaysia

Marking of Parts/ Traceability of Change: Changed material can be identified by date code or lot code

**Qualification Plan:** 

DEVICE NAME: UG3SC120009K4S PACKAGE : Gen 3 TO-247 parts

Test	Specification	Condition	Interval
H3TRB	JESD22-A101	Temp = 85C, RH=85%, bias = 80% of rated V or 100V max	1008 h
Temp Cycling	JESD22-A104	Temp = -55°C to +150°C; for 1000 cycles	1000 cycles
Autoclave	JESD22-A102	121°C/100% RH/15 PSIG for 96 hrs	96 h
IOL	MIL STD750, M 1037 AEC Q101	Ta=+25°C, deltaTj=125°C max, 5 min = Ton=Toff (pkg dependent)	3000 cycles
Resistance to Solder Heat	JESD22-B106	Ta=268°C 10 sec dwell	
Solderability	J STD 002	Ta=245C 5 sec dwell	

**QV DEVICE NAME: UF3SC120040B7S** 

PACKAGE: TO-263-7L parts, and E1B Modules

Test	Specification	Condition	Interval
MSL Preconditioning	J STD 020, JESD22-A113	MSL Conditions and IR reflow at 260C	
H3TRB	JESD22-A101	Temp = 85C, RH=85%, bias = 80% of rated V or 100V max	1008 h
Temp Cycling	JESD22-A104	Temp = -55°C to +150°C; for 1000 cycles	1000 cycles
Autoclave	JESD22-A102	121°C/100% RH/15 PSIG for 96 hrs	96 h
IOL	MIL STD750, M 1037 AEC Q101	Ta=+25°C, deltaTj=125°C max, 5 min = Ton=Toff (pkg dependent)	3000 cycles
Resistance to Solder Heat	JESD22-B106	Ta=268°C 10 sec dwell	
Solderability	J STD 002	Ta=245C 5 sec dwell	

TEM001791 Rev. I Page 2 of 3



# Initial Product/Process Change Notification

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QV DEVICE NAME: UG4SC120009K4SH PACKAGE : Gen 4 TO-247 parts

Test	Specification	Condition	Interval
H3TRB	JESD22-A101	Temp = 85C, RH=85%, bias = 80% of rated V or 100V max	1008 h
Temp Cycling	JESD22-A104	Temp = $-55$ °C to $+150$ °C; for 1000 cycles	1000 cycles
Autoclave	JESD22-A102	121°C/100% RH/15 PSIG for 96 hrs	96 h
IOL	MIL STD750, M 1037 AEC Q101	Ta=+25°C, deltaTj=125°C max, 5 min = Ton=Toff (pkg dependent)	3000 cycles
Resistance to Solder Heat	JESD22-B106	Ta=268°C 10 sec dwell	
Solderability	J STD 002	Ta=245C 5 sec dwell	

Estimated date for qualification completion: 30 April 2025

**Electrical Characteristics Summary:** Electrical characteristics are not impacted.

#### **List of Affected Parts:**

**Note:** Only the standard (off the shelf) part numbers are listed in the parts list. Any custom parts affected by this PCN are shown in the customer specific PCN addendum in the PCN email notification, or on the <u>PCN Customized Portal</u>.

Current Part Number	New Part Number	Qualification Vehicle
UF3SC065007K4S	#NONE	UG4SC120009K4SH
UJ4SC075006K4S	#NONE	UG4SC120009K4SH
UJ4SC075011K4S	#NONE	UG4SC120009K4SH
UF4SC120030K4S	#NONE	UG4SC120009K4SH
UF4SC120023K4S	#NONE	UG4SC120009K4SH
UJ4SC075009K4S	#NONE	UG4SC120009K4SH
UF3SC120009K4S	#NONE	UG3SC120009K4S
UF3SC120016K3S	#NONE	UG3SC120009K4S
UG3SC120009K4S	#NONE	UG3SC120009K4S
UF3SC120016K4S	#NONE	UG3SC120009K4S
UF3SC065040B7S	#NONE	UF3SC120040B7S
UJ4SC075011B7S	#NONE	UF3SC120040B7S
UJ4SC075018B7S	#NONE	UF3SC120040B7S
UF3SC065030B7S	#NONE	UF3SC120040B7S
UF3SC120040B7S	#NONE	UF3SC120040B7S
UJ4SC075009B7S	#NONE	UF3SC120040B7S

TEM001791 Rev. I Page 3 of 3